

# OL-LPC5410

wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included)

8 February 2016

Package information

## 1. Package summary

<b>Terminal position code</b>	B (bottom)
<b>Package type descriptive code</b>	WLCSP
<b>Package type industry code</b>	WLCSP
<b>Package style descriptive code</b>	UC (uncased chip)
<b>Package style suffix code</b>	NA (not applicable)
<b>Package body material type</b>	P (plastic)
<b>Mounting method type</b>	S (surface mount)
<b>Issue date</b>	3-11-2014

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		3.258	-	3.288	3.318	mm
E	package width		3.258	-	3.288	3.318	mm
A	seated height		0.5	-	0.54	0.58	mm
e	nominal pitch		-	-	0.4	-	mm
n <sub>2</sub>	actual quantity of termination		-	-	49	-	



## 2. Package outline

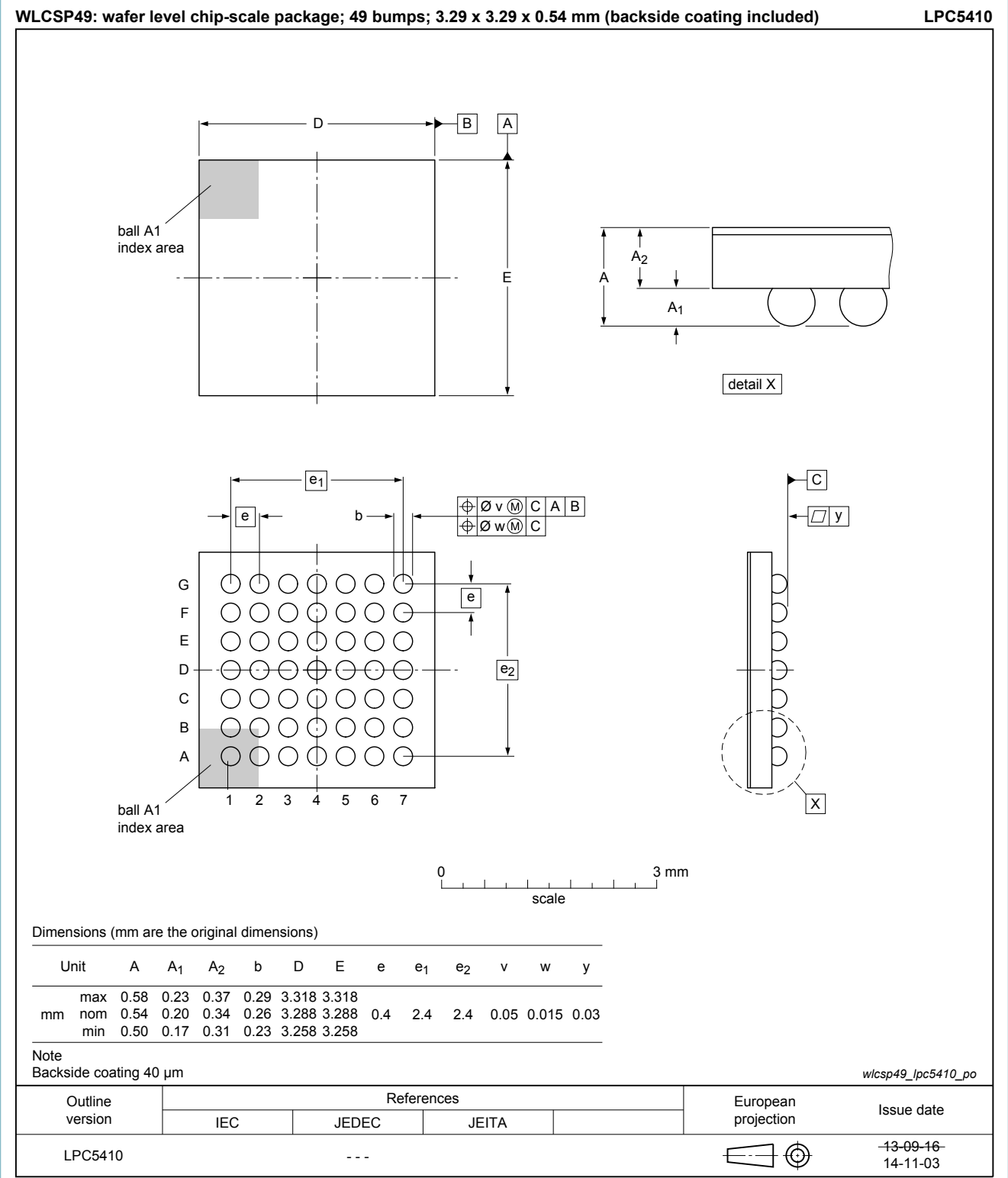


Fig. 1. Package outline WLCSP (OL-LPC5410)

wafer level chip-scale package; 49 bumps; 3.29 x 3.29 x 0.54 mm (backside coating included)

3. Soldering

Footprint information for reflow soldering of WLCSP49 package

LPC5410\_NSMD

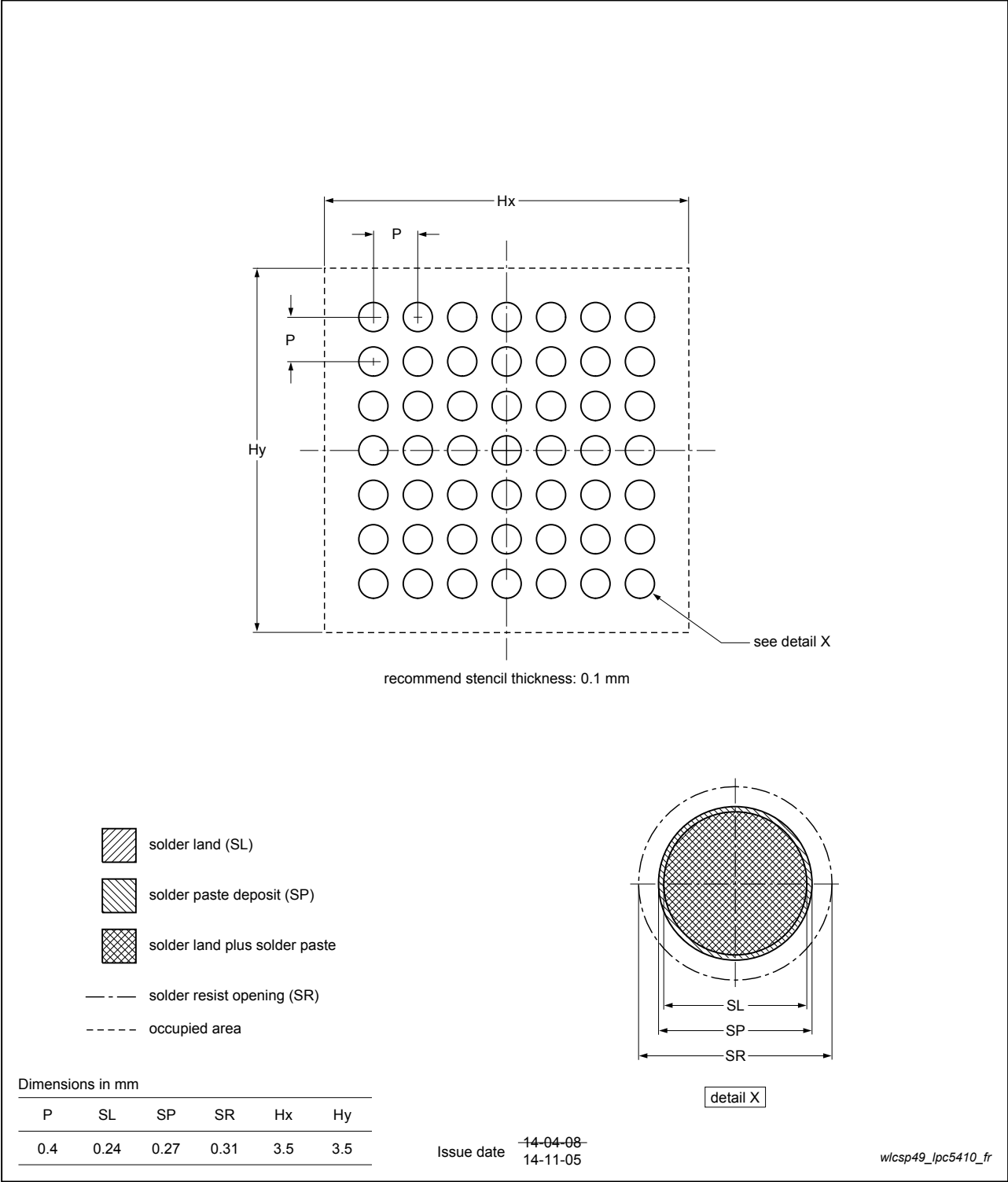


Fig. 2. Wave soldering footprint for WLCSP (OL-LPC5410)

wafer level chip-scale package; 49 bumps; 3.29 x  
3.29 x 0.54 mm (backside coating included)

## 4. Legal information

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